

## EAST Search History

| Ref # | Hits | Search Query   | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|--|---|------------------|---------|------------------|
| S1    | 3    | ("3354022").PN.  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:03 |
| S2    | 1006 | (216/2).CCLS.  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:05 |
| S3    | 458  | ((hydrophobic or water-repell\$5) and etch\$3).clm.                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:06 |
| S4    | 178  | ((hydrophobic or water-repell\$5) and etch\$3 and silicon).clm.        | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:06 |
| S5    | 215  | (hydrophobic or water-repell\$5).ti. and etch\$3                       | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:07 |
| S6    | 89   | (hydrophobic or water-repell\$5).ti. and etch\$3 and silicon           | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:13 |
| S7    | 550  | (hydrophobic or water-repell\$5).ti. and (die or etch\$3 or mold)      | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:13 |
| S8    | 31   | (hydrophobic or water-repell\$5).ti. and (die or etch\$3 or mold).clm. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:22 |
| S9    | 9    | (fluoroalkylsilane and etch\$3).clm.                                   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | OFF     | 2006/03/18 18:22 |

## EAST Search History

|     |       |   |   |    |     |                  |
|-----|-------|---|---|----|-----|------------------|
| S10 | 81    | (hydrophobic or water-repell\$5).ti. and fluoroalkylsilane\$1   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/03/18 18:23 |
| S11 | 0     | (hydrophobic or water-repell\$5) and fluoroalkylsilane\$1 and etch\$3                                   | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR | OFF | 2006/03/18 18:24 |
| S12 | 530   | (hydrophobic or water-repell\$5 or fluoroalkylsilane\$1) and etch\$3                                    | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR | OFF | 2006/05/03 14:02 |
| S13 | 526   | (hydrophobic or water-repell\$5) and etch\$3  | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR | OFF | 2006/03/18 18:25 |
| S14 | 4     | fluoroalkylsilane\$1 and etch\$3  | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR | OFF | 2006/03/18 18:24 |
| S15 | 400   | (hydrophobic or water-repell\$5) and mold   | EPO; JPO;<br>DERWENT;<br>IBM_TDB                        | OR | OFF | 2006/03/18 18:25 |
| S16 | 714   | (428/161).CCLS.   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/05/03 13:16 |
| S17 | 17    | (hydrophobic or water-repell\$5) and S16  | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/05/03 13:20 |
| S18 | 23211 | (hydrophobic or water-repell\$5) and (etch\$3 or photolithograph\$4 or lithograph\$7)                   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/05/03 13:21 |
| S19 | 401   | (hydrophobic or water-repell\$5) and (etch\$3 or photolithograph\$4 or lithograph\$7)                   | JPO   | OR | OFF | 2006/05/03 13:21 |
| S20 | 44    | (hydrophobic or water-repell\$5) and (etch\$3 or photolithograph\$4 or lithograph\$7) and silicon       | JPO   | OR | OFF | 2006/05/03 13:25 |
| S21 | 1924  | (hydrophobic or water-repell\$5).clm. and (etch\$3 or photolithograph\$4 or lithograph\$7) and silicon  | US-PGPUB;<br>USPAT                                      | OR | OFF | 2006/05/03 13:26 |
| S22 | 911   | (hydrophobic or water-repell\$5).clm. and (etch\$3 or photolithograph\$4 or lithograph\$7) same silicon | US-PGPUB;<br>USPAT                                      | OR | OFF | 2006/05/03 13:26 |

## EAST Search History

|     |       |  |   |    |     |                  |
|-----|-------|--|---|----|-----|------------------|
| S23 | 277   | (hydrophobic or water-repell\$5).ab. and (etch\$3 or photolithograph\$4 or lithograph\$7) same silicon   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 13:31 |
| S24 | 1882  | (hydrophobic or water-repell\$5) with (etch\$3 or photolithograph\$4 or lithograph\$7)   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:49 |
| S25 | 1028  | S24 and silicon  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 13:32 |
| S26 | 948   | (hydrophobic or water-repell\$5 or fluoroalkylsilane\$1 or polyfluoroethylene or ptfe or polytetrafluoroethylene) and etch\$3  | EPO; JPO; DERWENT; IBM_TDB                  | OR | OFF | 2006/05/03 14:02 |
| S27 | 144   | (hydrophobic or water-repell\$5 or fluoroalkylsilane\$1 or polyfluoroethylene or ptfe or polytetrafluoroethylene) and etch\$3 and silicon  | EPO; JPO; DERWENT; IBM_TDB                  | OR | OFF | 2006/05/03 16:45 |
| S28 | 114   | ((karasawa near2 yasushi) (mitsuro near3 atobe near3 chino)).in.   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:47 |
| S29 | 26    | ((karasawa near2 yasushi) (mitsuro near3 atobe near3 chino)).in. and repell\$4   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:49 |
| S30 | 39    | ((karasawa near2 yasushi) (mitsuro near3 atobe near3 chino)).in. and (ink adj jet)   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:49 |
| S31 | 9     | ((karasawa near2 yasushi) (mitsuro near3 atobe near3 chino)).in. and (ink adj jet) and etch\$3   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:50 |
| S32 | 11861 | (hydrophobic or (water adj repell\$4) or water\$1repell\$4) and (ink\$1jet (ink adj jet) or silicon) and etch\$3   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:52 |
| S33 | 2311  | (hydrophobic or (water adj repell\$4) or water\$1repell\$4) and (ink\$1jet (ink adj jet) or silicon) and etch\$3 and (fluoroalkylsilane\$1 or polyfluoroethylene or ptfe or polytetrafluoroethylene or fluoropolymer\$1) | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 16:53 |

## EAST Search History

|     |      |   |   |    |     |                  |
|-----|------|---|---|----|-----|------------------|
| S34 | 349  | (hydrophobic or (water adj repell\$4) or water\$1repell\$4).clm. and (ink\$1jet (ink adj jet) or silicon) and etch\$3 and (fluoroalkylsilane\$1 or polyfluoroethylene or ptfe or polytetrafluoroethylene or fluoropolymer\$1) | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:07 |
| S35 | 3    | (hydrophobic or (water adj repell\$4) or water\$1repell\$4) and etch\$3 and (fluoroalkylsilane\$1 or polyfluoroethylene or ptfe or polytetrafluoroethylene or fluoropolymer\$1)   | JPO   | OR | OFF | 2006/05/03 16:55 |
| S36 | 682  | photosensitive adj glass and pattern\$3   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:06 |
| S37 | 592  | photosensitive adj glass and etch\$3  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:06 |
| S38 | 3746 | (hydrophobic or (water adj repell\$4) or water\$1repell\$4) and (silicon near10 etch\$3)  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:07 |
| S39 | 114  | (hydrophobic or (water adj repell\$4) or water\$1repell\$4) with (silicon near10 etch\$3)   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:07 |
| S40 | 1    | (hydrophobic or water-repell\$5) with silicon with (etch\$3 and (photoresist or \$5lithograpy))   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 17:55 |
| S41 | 25   | (etch with silicon with anisotropic with mask\$3 with oxide) .clm.  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:02 |
| S42 | 5498 | (etch with silicon with mask\$3 with oxide)w near20 (hydrophobic or (water adj repell\$3))  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:04 |
| S43 | 2    | (etch with silicon with mask\$3 with oxide) near20 (hydrophobic or (water adj repell\$3))   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:05 |
| S44 | 253  | (etch with silicon with mask\$3 with oxide) and (hydrophobic or (water adj repell\$3))  | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:04 |
| S45 | 924  | (hydrophobic or (water adj repell\$3)) with etch\$3   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:05 |
| S46 | 646  | (hydrophobic or (water adj repell\$3)) with etch\$3 and silicon   | US-PGPUB; USPAT                             | OR | OFF | 2006/05/03 18:05 |
| S47 | 3    | ("3354022").PN.   | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | OFF | 2006/05/03 18:21 |
| S48 | 23   | ("3354022").URPN.   | USPAT                                       | OR | OFF | 2006/05/03 19:05 |

## EAST Search History

|     |   |                 |   |    |     |                  |
|-----|---|-----------------|---|----|-----|------------------|
| S49 | 2 | ("2760863").PN. | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | OFF | 2006/05/03 19:06 |
| S50 | 2 | ("2760863").PN. | US-PGPUB;<br>USPAT;<br>USOCR                            | OR | OFF | 2006/05/03 19:06 |